

Appln No. 10/659,017
Amdt. Dated August 5, 2005
Response to Office Action of July 1, 2005

4

REMARKS/ARGUMENTS

Applicant thanks Examiner for the detailed Office Action dated July 1, 2005. In response to the issues raised, Applicant offers the following submissions and amendments.

Amendments

Claim 1 has been amended to clarify that the invention is directed to an integrated circuit fabricated on a single micro-chip wafer substrate. This clarification of the substrate is consistent with the semiconductor etching and deposition fabrication techniques described throughout the specification. Accordingly, the amendments do not introduce any new matter.

Claims 1 to 5 - Obviousness

Claims 1 to 5 stand rejected as obvious in light of US 4,663,743 to Rampuria et al, in view of US 5,408,590 to Dvorsak.

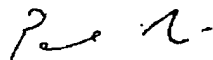
Amended claim 1 further defines the term 'substrate' to be a 'micro-chip wafer substrate'. Neither of the citations disclose the elements of claim 1 incorporated onto a single micro-chip wafer substrate. Therefore the cited references fail to support a rejection under the provisions of 35 USC§103.

Likewise, claims 2 to 5 are similarly non-obvious by virtue of their appendance to claim 1.

In light of the above, it is respectfully submitted that all of the Examiner's rejections have been successfully traversed. The Applicant believes that the application is now in condition for allowance and favorable reconsideration of the application is courteously solicited.

Very respectfully,

Applicant:



PAUL LAPSTUN

Applicant:



KIA SILVERBROOK

C/o:

Silverbrook Research Pty Ltd
393 Darling Street
Balmain NSW 2041, Australia

Appln No. 10/659,017
Amdt. Dated August 5, 2005
Response to Office Action of July 1, 2005

5

Email: kia.silverbrook@silverbrookresearch.com
Telephone: +612 9818 6633
Facsimile: +61 2 9555 7762